mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









HSP Series Thermal Pads

- Easy-to-use thermal interface Material designed for use with Standard Crydom single-phase and three-phase solid-state relays.
- Excellent alternative to thermal grease
- Adhesive on one side

HSP-2

For use with all single phase Panel mount SSR's, Control modules and M50 power modules.

HSP-5

For use will all three phase panel mount SSR's (53TP/53RV).

HSP-6

For use with EL Series panel mount SSR's.

TYPICAL PROPERTIES

Control Voltage	HSP-2/HSP-5/HSP-6	
Color	Black	
Thickness, inch (mm)	0.005 (0.127)	
Adhesive One Side	Yes	
Thermal Impeadance [°C-in²/W] (1)	0.48 @25 psi	
Thermal Conductivity [W/m-K]	2.0	
Flame Rating	V-0	
Continuous Temperature Range [°C]	-60 to 180	
Volume Resistivity [ohm-cm]	10 ² Ohm	

GENERAL NOTES

(1) This value is provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Rev. 082214





MECHANICAL SPECIFICATIONS

Tolerances: ±0.010 in / 0.3 mm All dimensions are in: inches [millimeters]



ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People's Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

Part	Toxic or hazardous Substance and Elements						
Name	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)	
Semiconductor die	Х	0	0	0	0	0	
Solder	X	0	0	0	0	0	

附件 - 环保信息

此附件所标示的包括电子信息产品污染图标的环保信息符合中华人民共和国电子行业标准 SJ/T11364 - 2006, 电子信息产品污染控制标识要求。

部件	有毒有害物质或元素							
名称	铅 汞 镉		镉	六价铬	多溴联苯	多溴二苯醚		
	(Pb)	(Hg)	(Cd)	(Cr (VI))	(PBB)	(PBDE)		
半导体芯片	X	0	0	0	0	0		
焊接点	X	0	0	0	0	0		



